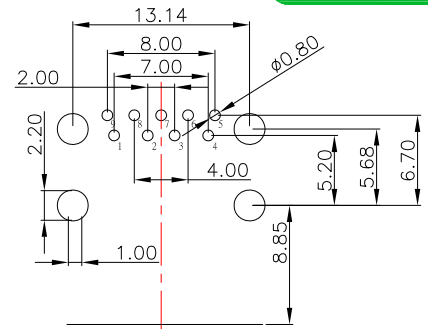
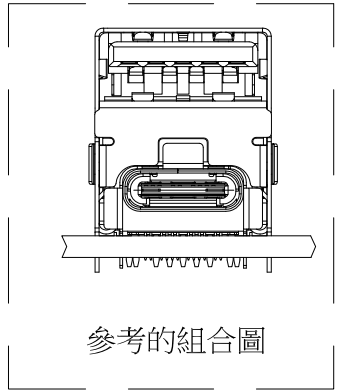
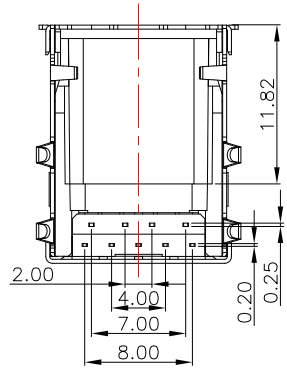




# SUA-110H15-30x-S242

鍍層厚度:

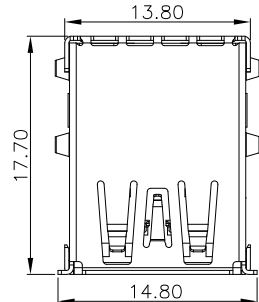
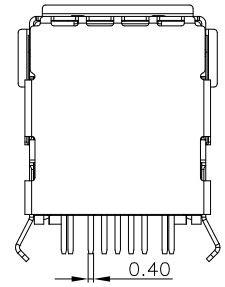
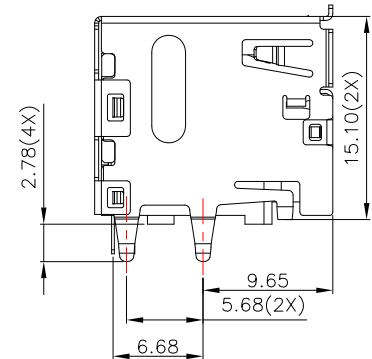
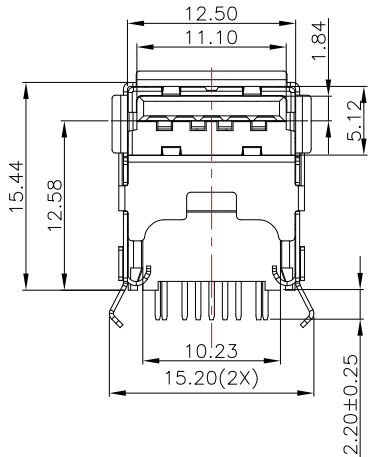
Blank	: 1u"
2	: 15u"
3	: 30u"



## RECOMMENDED PCB LAYOUT

### NOTE:

- MATERIAL:
  - Housing: PA9T
  - Contact: PHOSPHOR BRONZE
  - Shell: SUS
- Finish:
  - Contact: Plated Gold in Mating Area ;  
Tin Plated on Solder Balls ;  
Nickel under plated overall
  - Shell: Nickel under Plated surface layer
- SPECIFICATION:
  - Current Rate: 1.8 A
  - insulator Resistance: 100MΩ Min
  - Dielectric Strength: 100V AC
  - Contact Resistance: 30mΩ Max
  - Operation Temperature: -40°C ~ +85°C
  - Insertion Force: 35 N
  - Extraction Force: 10 N



Pin #	SIGNAL NAME
1	VBUS
2	D-
3	D+
4	GND
5	StdA_SSRX-
6	StdA_SSRX+
7	GND_DRAIN
8	StdA_SSTX-
9	StdA_SSTX+
Shell	Shield



TOLERANCE UNLESS OTHERWISE STATED:

Up to 5	±0.2
Above 5 ~ 15	±0.3
Above 15 ~ 30	±0.4
Above 30 ~ 50	±0.5
Angle	±0.3°

3RD. ANGEL'S

UNITS: MM

DRAWN BY:	DATE	MAT'L	TITLE	CONNECTOR
Jack Lu	04/22/22			
CHECKED BY:	DATE	FINISH	MODLE	USB3.0+TYPEC 彎腳 H=15.44mm
Jacky Chen	04/22/22			
APPROVED BY:	DATE	SCALE	DWG NO.	SUA-110H15-30x-S242
Tony Kao	04/22/22	1 : 1	PART NO.	SUA-110H15-30x-S242
		SHEET NO.	1 of 1	
				SIZE: A4
				VER: R

ITEM NO.	DESCRIPTION	DRAWN	DATE